

DESCRIPTION and APPLICATIONS

Suitable for AC to DC bridge full wave rectification for SMPS, LED lighting, adapter, battery charger, home appliances, office equipment, and telecommunication applications.

VOLTAGE RANGE

50 to 1000 Volts

CURRENT

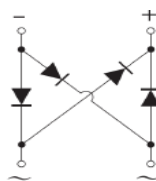
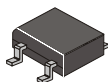
1.0Ampere

FEATURES

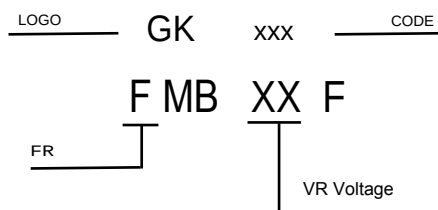
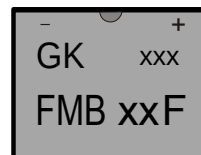
- * Ideal for printed circuit board
- * Reliable low cost construction utilizing molded plastic technique
- * High surge current capability

MECHANICAL DATA

- * Polarity: Symbol molded on body
- * Mounting position: Any



Internal Schematic



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

TYPE NUMBER	FMB05F	FMB1F	FMB2F	FMB4F	FMB6F	FMB8F	FMB10F	UNIT
Maximum Recurrent Peak Reverse Voltage	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current	1.0							A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	30							A
Maximum Forward Voltage Drop per Bridge Element at 0.5A D.C.	1.3							V
Maximum DC Reverse Current Ta=25°C	5.0							μA
at Rated DC Blocking Voltage Ta=100°C	200							μA
Maximum Reverse Recovery Time (Note 1)	500							nS
Typical Junction Capacitance (Note 2)	12							pF
Typical Thermal Resistance R JA (Note 3)	80							°C/W
Operating and Storage Temperature Range Tj, Tstg	-65 — +150							°C

NOTES:

1. Reverse Recovery Time test condition: IF=0.5A, IR=1.0A, IRR=0.25A
2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
3. Thermal Resistance from Junction to Ambient.

RATING AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

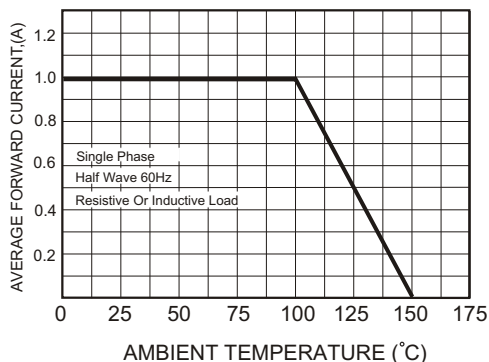


FIG.2-TYPICAL FORWARD CHARACTERISTICS

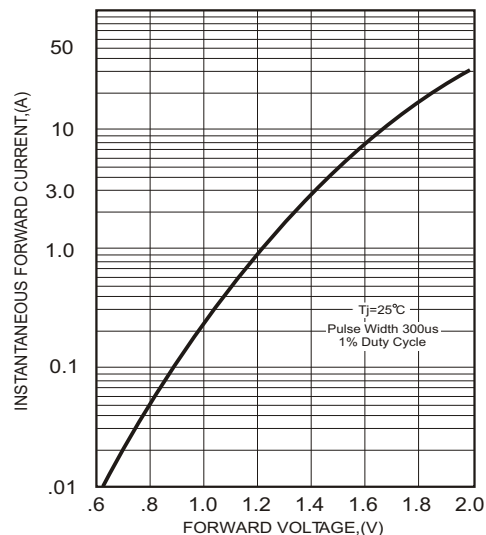


FIG.3 - TYPICAL REVERSE CHARACTERISTICS

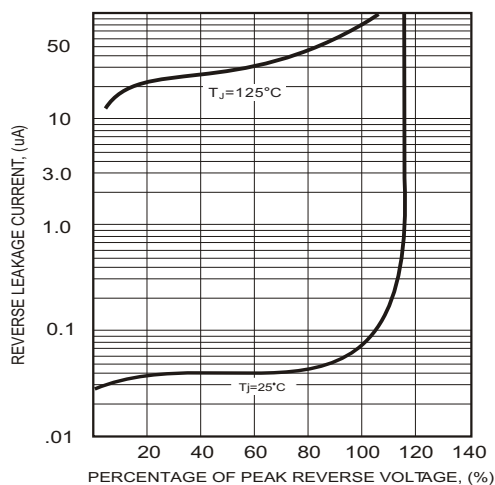


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

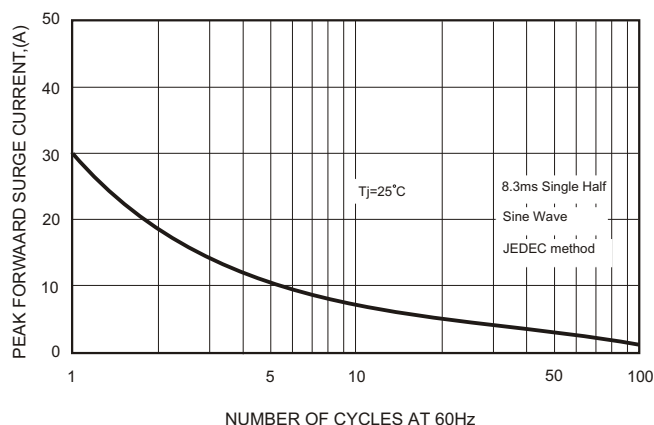
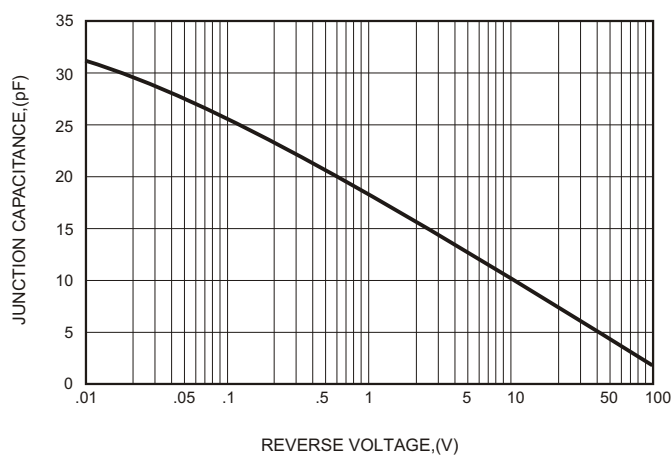


FIG.5-TYPICAL JUNCTION CAPACITANCE



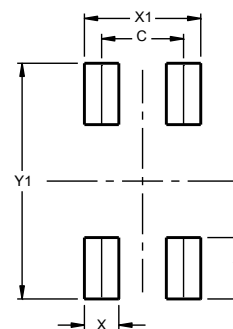
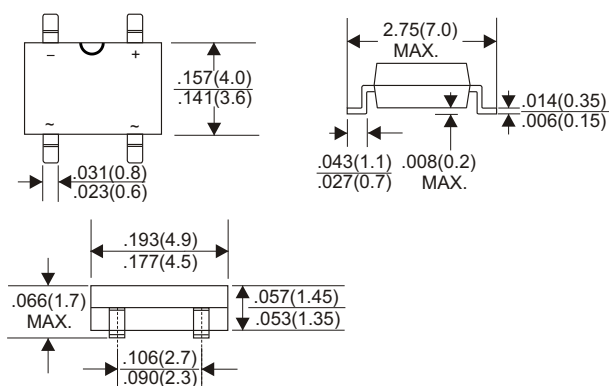
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150 °C
	-Temperature Max($T_{s(max)}$)	+200 °C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3 °C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3 °C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217 °C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5) °C
Time within 5 °C of actual Peak Temp (t_P)		30 secs. Max
Ramp-down Rate		6 °C/sec. Max
Time 25 °C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260 °C



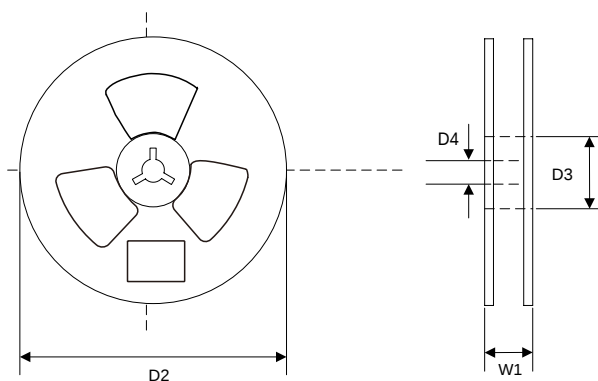
Package Dimensions & Suggested Pad Layout

MBF



Dimensions	Value (in mm)
C	2.50
X	1.10
X1	3.60
Y	2.10
Y1	7.50

Tape



Quantity: 5000PCS